PRODUCT NO.	POSITION	REMARK	DIM "C"	DIM "D"	DIM "E"
10053363-100LF	2 X 3 2	WITH KEY	54.61	54.46	3.50±0.25
10053363-200LF	2 X 3 2	WITHOUT KEY	N/A	N / A	3.50±0.25
10053363-201LF	2 X 3 2	WITHOUT KEY	N/A	N/A	2.60±0.10

Α

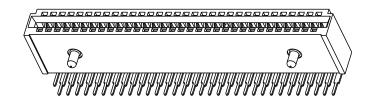
NOTES:

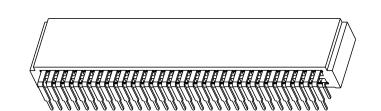
I. MATERIALS:

HOUSING: HIGH TEMPERATURE THERMOPLASTIC, UL 94V-0 RATED, BLACK. TERMINAL: HIGH CONDUCTIVITY COPPER ALLOY.

CONTACT AREA: 30u" GOLD OVER 50u" NICKEL UNDERPLATED. SOLDER TAIL: 100u" TIN OVER 50u" NICKEL UNDERPLATED.

- 2. PRODUCT PERFORMANCE SPEC. PER GS-12-259.
- 3. PACKAGE SPECIFICATION PER GS-14-937.
- 4. PART NUMBER 10053363-X00LF MEETS EUROPEAN UNION DIRECTIVE AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008. THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C±5°C PEAK TEMPERATURE FOR 10 SECONDS IN A REFLOW SOLDER APPLICATION WITH A CIRCUIT BOARD.
- 5. MANUFACTURER'S NAME, P/N AND DATE CODE TO APPEAR ON THIS SURFACE AS PER GS-24-007.





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C

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spec ref	*			dr	wcadmin		2006/08/07	proje	ection	1 1	.,	size	scale	
tolerance std TOLE		OLERANCES UNLESS THERWISE SPECIFIED		eng	Wei-Long Zhang	nang 2012/06/06		7			l MM		1.000	1.000
				chr -		-				-		ecn no	ELX-DG-01	ELX-DG-011840-1
		OTHERWISE STECTIFED		appr	Pei-Ming Zheng		2012/06/06	product	family			rel level	Relea	ase
surface / line		0.X	±0.30	CC:	–° 2X32P RIGHT		T ANCI	T ANCIE		0 0			re	
	linear	linear 0.XX ±0.15	F '			2 x 3 2 r	I ANG	ANGLE		5 100		53	l	
		0.XXX		 +		+ POW	OWER CARD EDGE				× o			K
	angular	0°	+2°	www	fcicom	cat no)	*	Pr	oduct -	Customer	Drw	sheet Lof	3

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Pro/E File - REV C - 2009-06-09

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PDS: Rev :K

STATUS:Released

Printed: Jun 06, 2012

